



Material Content Data Sheet



Sales Product Name				BSC014N03LS G		Issued		24. January 2018	
MA#				MA001268784					
Package				PG-TDSON-8-7		Weight*		119.41 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	1.396	1.17	1.17	11690	11690	
leadframe	inorganic material	phosphorus	7723-14-0	0.011	0.01		95		
	non noble metal	iron	7439-89-6	0.038	0.03		317		
	non noble metal	copper	7440-50-8	37.762	31.62	31.66	316238	316650	
	noble metal	gold	7440-57-5	0.039	0.03	0.03	325	325	
wire	organic material	carbon black	1333-86-4	0.086	0.07		719		
encapsulation	plastics	epoxy resin	-	6.098	5.11		51066		
	inorganic material	silicondioxide	60676-86-0	36.758	30.78	35.96	307833	359618	
leadfinish	non noble metal	tin	7440-31-5	1.452	1.22	1.22	12157	12157	
plating	noble metal	silver	7440-22-4	0.166	0.14	0.14	1386	1386	
solder	non noble metal	tin	7440-31-5	0.039	0.03		326		
	noble metal	silver	7440-22-4	0.049	0.04		408		
	non noble metal	lead	7439-92-1	1.862	1.56	1.63	15590	16324	
	inorganic material	phosphorus	7723-14-0	0.003	0.00		28		
heatspreader	non noble metal	iron	7439-89-6	0.011	0.01		95		
	non noble metal	copper	7440-50-8	11.320	9.48	9.49	94801	94924	
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.007	0.01		56		
	non noble metal	iron	7439-89-6	0.022	0.02		187		
	non noble metal	copper	7440-50-8	22.292	18.67	18.70	186683	186926	
*deviation	< 10%			Sum in total:		100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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